

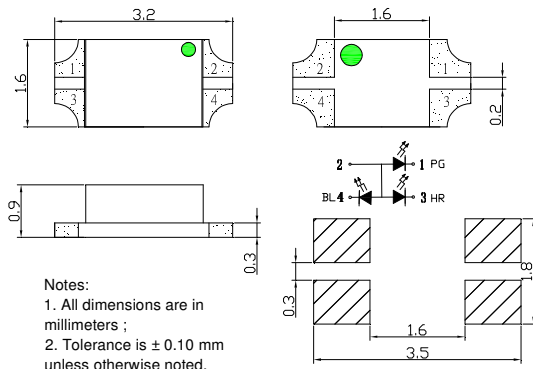
■Features

- Full-Color
- Super high brightness of surface mount LED
- Water Clear Flat Mold
- Compact package outline
(LxWxT) of 3.2mm x 1.6mm x 0.9mm
- Compatible to IR reflow soldering.

■Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

■Outline Dimension



Notes:
1. All dimensions are in millimeters ;
2. Tolerance is ± 0.10 mm unless otherwise noted.

Recommended Soldering Pattern
(Units : mm)

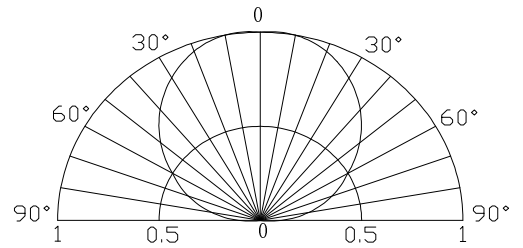
■Absolute Maximum Rating

(Ta=25°C)

Item	Symbo l	Value		Unit
		HR	PG/BL	
DC Forward Current	I _F	30	30	mA
Pulse Forward Current*	I _{FP}	100	100	mA
Reverse Voltage	V _R	5	5	V
Power Dissipation	P _D	78	108	mW
Operating Temperature	Topr	-40 ~ +85		°C
Storage Temperature	Tstg	-40~ +85		°C
Lead Soldering Temperature	Tsol	260°C/10sec		-

*Pulse width Max 0.1ms, Duty ratio max 1/10

■Directivity



■Electrical -Optical Characteristics

(Ta=25°C)

Part Number	Color		V _F (V)			I _R (μA)	I _v (mcd)			λD(nm)			2θ1/2(deg)
			Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.
			I _F =20mA			V _R =5V	I _F =20mA						
OSTB1206C1E-A	Blue	BL	2.8	2.9	3.6	10	100	200	-	460	466	472	120
	Pure Green	PG	2.8	2.9	3.6	10	400	600	-	515	520	525	120
	Red	HR	1.8	2.0	2.6	10	100	200	-	615	620	625	120

*1 Tolerance of measurements of dominant wavelength is ±1nm

*2 Tolerance of measurements of luminous intensity is ±15%

*3 Tolerance of measurements of forward voltage is±0.1V

■ **Cautions:**

1. After open the package, the LED's floor life is 1 year under 30°C or less and 60%RH or less (MSL:2).
2. Heat generation must be taken into design consideration when using the LED.
3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.
8. OPTOSUPPLY will not do 4M change without advance consultation.